



Applications

Gap filler for heatsinks to CPUs, LEDs, and electronic components with low to zero stress

Semiconductor low-pressure or spring clamp mounting

EV battery packs & cooling components to chassis

Gaming systems (PCs & consoles)

Telecommunications equipment

Power supplies

Available Packaging

8327GL5-30ML	Cartridge	28.7 mL, 66 g
8327GL5-180ML	Cartridge	127 mL, 294 g

Links

- Technical Data Sheet
- Safety Data Sheet
- 🖻 Category Data Sheet
- ? Technical Inquires







8327GL5 Non-silicone Liquid Thermal Gel, 5 W/(m-K)

8327GL5 is a 1-part, silicone-free, high temperature, soft gel offering very high thermal conductivity and flame retardancy. This form-in-place, non-curable gel is easy to dispense and conforms to the component/ heatsink interface, ensuring all air is displaced and eliminating hotspots. Since the gel does not cure, circuits can be powered up immediately following application, offering exceptional convenience.

Very high thermal conductivity

Flame retardant—meets UL94 V-0

High temperature stability

Zero pump out—no slump under low pressure

Silicone-free, will not contaminate surfaces

Low modulus, ideal for aggressive thermal cycling conditions

